

***Status of the Claims***

The listing of claims will replace all prior versions, and listings of claims in the application.

1. (Original) In a multiple stage, multiple exposure lithography system, a method comprising:

- processing a first pair of wafers;
- exchanging the first pair of wafers to pattern each sequentially using a first reticle;
- exchanging the first reticle for a second reticle;
- exchanging the first pair of wafers to pattern each sequentially using the second reticle;
- exchanging the first pair of wafers for a second pair of wafers;
- processing the second pair of wafers;
- exchanging the second pair of wafers to pattern each sequentially using the second reticle;
- exchanging the first and second reticles; and
- exchanging the second pair of wafers to pattern each sequentially using the first reticle.

2-3 (Cancelled)

4. (Original) In a multiple stage, multiple exposure lithography system, a method comprising:

- processing a first pair of wafers;
- exchanging the first pair of wafers to pattern each sequentially using a first reticle;
- exchanging the first reticle for a second reticle;
- exchanging the first pair of wafers to pattern each sequentially using the second reticle;
- exchanging a first one of the first pair of wafers for a first one of a second pair of wafers;
- processing the first one of the second pair of wafers;
- exchanging the second reticle for the first reticle;
- exchanging the second one of the first pair of wafers for a second one of the second pair of wafers;
- processing the second one of the second pair of wafers;
- exchanging the second pair of wafers to pattern each sequentially using the first reticle;
- exchanging the first and second reticles; and
- exchanging the second pair of wafers to pattern each sequentially with the second reticle.

5. (Cancelled)